

# 100V, 150 mA Constant On-Time Buck Switching Regulator

Check for Samples: [SM72485](#)

## FEATURES

- Renewable Energy Grade
- Operating Input Voltage Range: 6V to 95V
- Integrated 100V, N-Channel Buck Switch
- Internal Start-Up Regulator
- No Loop Compensation Required
- Ultra-Fast Transient Response
- On Time Varies Inversely With Input Voltage
- Operating Frequency Remains Constant With Varying Line Voltage and Load Current
- Adjustable Output Voltage From 2.5V
- Highly Efficient Operation
- Precision Internal Reference
- Low Bias Current
- Intelligent Current Limit
- Thermal Shutdown
- Package
  - VSSOP
  - WSON (4mm x 4mm)

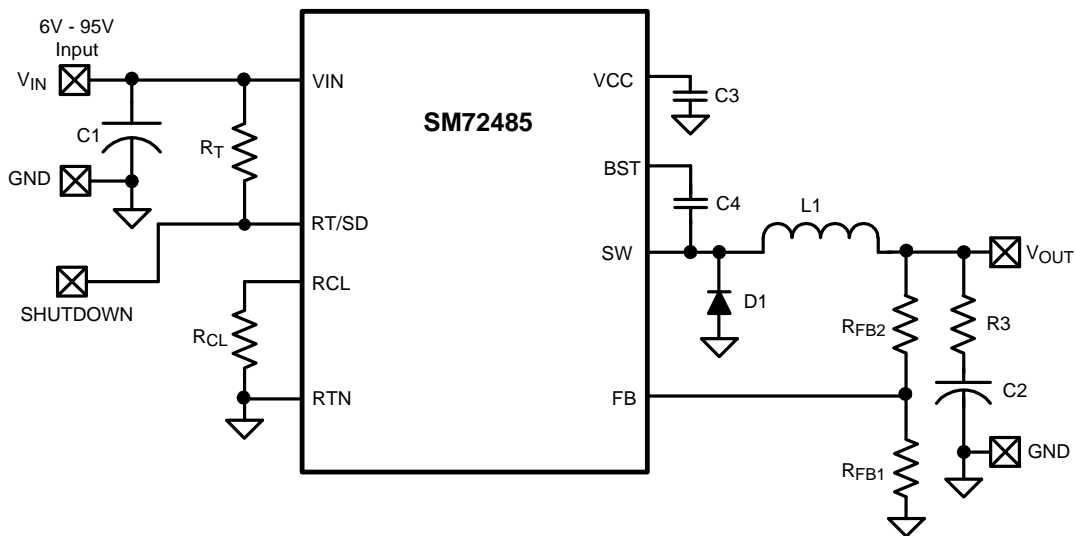
## APPLICATIONS

- PV Panel Smart Junction Boxes
- Non-Isolated Telecommunication Buck Regulator
- Secondary High Voltage Post Regulator
- +42V Automotive Systems

## DESCRIPTION

The SM72485 Step Down Switching Regulator features all of the functions needed to implement a low cost, efficient, Buck bias regulator. This high voltage regulator contains an 100 V N-Channel Buck Switch. The device is easy to implement and is provided in the VSSOP and the thermally enhanced WSON package. The regulator is based on a control scheme using an ON time inversely proportional to  $V_{IN}$ . This feature allows the operating frequency to remain relatively constant. The control scheme requires no loop compensation. An intelligent current limit is implemented with forced OFF time, which is inversely proportional to  $V_{OUT}$ . This scheme ensures short circuit control while providing minimum foldback. Other features include: Thermal Shutdown,  $V_{CC}$  under-voltage lockout, Gate drive under-voltage lockout, Max Duty Cycle limiter, and a pre-charge switch.

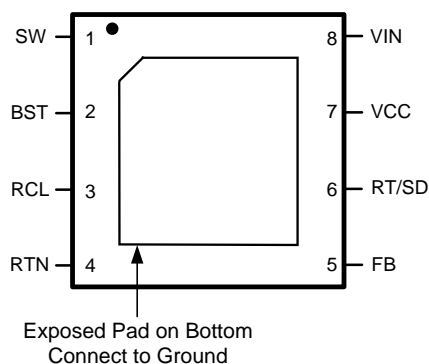
## Typical Application, Basic Step-Down Regulator



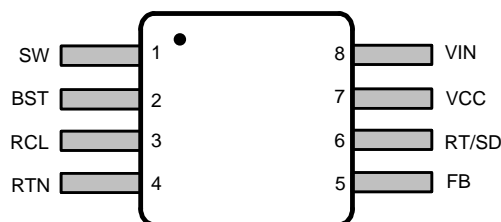
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## Connection Diagram



**Figure 1. Top View  
8-Lead WSON**



**Figure 2. Top View  
8-Lead VSSOP**

## PIN DESCRIPTIONS

| Pin | Name  | Description  | Application Information   |
|-----|-------|--|---|
| 1   | SW    | Switching Node   | Power switching node. Connect to the output inductor, re-circulating diode, and bootstrap capacitor.  |
| 2   | BST   | Boost Pin (Boot-strap capacitor input)                       | An external capacitor is required between the BST and the SW pins. A 0.01 $\mu\text{F}$ ceramic capacitor is recommended. An internal diode charges the capacitor from $V_{\text{CC}}$ during each off-time.  |
| 3   | RCL   | Current Limit OFF time set pin                               | A resistor between this pin and RTN sets the off-time when current limit is detected. The off-time is preset to 35 $\mu\text{s}$ if $\text{FB} = 0\text{V}$ .   |
| 4   | RTN   | Ground pin   | Ground for the entire circuit.  |
| 5   | FB    | Feedback input from Regulated Output                         | This pin is connected to the inverting input of the internal regulation comparator. The regulation threshold is 2.5V.   |
| 6   | RT/SD | On time set pin  | A resistor between this pin and $V_{\text{IN}}$ sets the switch on time as a function of $V_{\text{IN}}$ . The minimum recommended on time is 400 ns at the maximum input voltage. This pin can be used for remote shutdown.                                      |
| 7   | VCC   | Output from the internal high voltage series pass regulator. | This regulated voltage provides gate drive power for the internal Buck switch. An internal diode is provided between this pin and the BST pin. A local 0.47 $\mu\text{F}$ decoupling capacitor is required. The series pass regulator is current limited to 9 mA. |
| 8   | VIN   | Input voltage  | Input operating range: 6V to 95V.   |
|     | EP    | Exposed Pad  | The exposed pad has no electrical contact. Connect to system ground plane for reduced thermal resistance.   |



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

## Absolute Maximum Ratings<sup>(1)(2)</sup>

|   |                  |
|---|------------------|
| V <sub>IN</sub> to GND                            | -0.3V to 100V    |
| BST to GND  | -0.3V to 114V    |
| SW to GND (Steady State)                          | -1V              |
| ESD Rating <sup>(3)</sup>                         | Human Body Model |
| BST to V <sub>CC</sub>                            | 100V             |
| BST to SW   | 14V              |
| V <sub>CC</sub> to GND                            | 14V              |
| All Other Inputs to GND                           | -0.3 to 7V       |
| Lead Temperature (Soldering 4 sec) <sup>(4)</sup> | 260°C            |
| Storage Temperature Range                         | -55°C to +150°C  |

- (1) Absolute Maximum Ratings are limits beyond which damage to the device may occur. Operating Ratings are conditions under which operation of the device is intended to be functional. For ensured specifications and test conditions, see the Electrical Characteristics.
- (2) If Military/Aerospace specified devices are required, please contact the TI Sales Office/ Distributors for availability and specifications.
- (3) The human body model is a 100pF capacitor discharged through a 1.5kΩ resistor into each pin. The ESD rating for pin 2, pin 7, and pin 8 is 1 kV for HBM and 150V for MM.
- (4) For detailed information on soldering plastic VSSOP and WSON packages, refer to <http://www.ti.com/lit/SNOA549>.

## Operating Ratings<sup>(1)</sup>

|                                |                  |
|--------------------------------|------------------|
| V <sub>IN</sub>                | 6V to 95V        |
| Operating Junction Temperature | -40°C to + 125°C |

- (1) Absolute Maximum Ratings are limits beyond which damage to the device may occur. Operating Ratings are conditions under which operation of the device is intended to be functional. For ensured specifications and test conditions, see the Electrical Characteristics.

## Electrical Characteristics

Specifications with standard typeface are for T<sub>J</sub> = 25°C, and those with **boldface** type apply over full **Operating Junction Temperature range**. V<sub>IN</sub> = 48V, unless otherwise stated<sup>(1)</sup>.

| Symbol                        | Parameter                  | Conditions         | Min        | Typ | Max        | Units |
|-------------------------------|----------------------------|--------------------|------------|-----|------------|-------|
| <b>VCC Supply</b>             |                            |                    |            |     |            |       |
| Vcc Reg                       | Vcc Regulator Output       | Vin = 48V          | <b>6.6</b> | 7   | <b>7.4</b> | V     |
|                               | Vin – Vcc                  | 6V < Vin < 8.5V    |            | 100 |            | mV    |
|                               | Vcc Bypass Threshold       | Vin Increasing     |            | 8.5 |            | V     |
|                               | Vcc Bypass Hysteresis      |                    |            | 300 |            | mV    |
|                               | Vcc Output Impedance       | Vin = 6V           |            | 100 |            | Ω     |
|                               |                            | Vin = 10V          |            | 8.8 |            | Ω     |
|                               |                            | Vin = 48V          |            | 0.8 |            | Ω     |
|                               | Vcc Current Limit          | Vin = 48V          |            | 9.2 |            | mA    |
|                               | Vcc UVLO                   | Vcc Increasing     |            | 5.3 |            | V     |
|                               | Vcc UVLO hysteresis        |                    |            | 190 |            | mV    |
|                               | Vcc UVLO filter delay      |                    |            | 3   |            | μs    |
|                               | Iin Operating current      | FB = 3V, Vin = 48V |            | 550 | <b>750</b> | μA    |
|                               | Iin Shutdown Current       | RT/SD = 0V         |            | 110 | <b>176</b> | μA    |
| <b>Switch Characteristics</b> |                            |                    |            |     |            |       |
|                               | Buckswitch Rds(on)         | Itest = 200 mA     |            | 2.2 | <b>4.6</b> | Ω     |
|                               | Gate Drive UVLO            | Vbst – Vsw Rising  | <b>2.8</b> | 3.8 | <b>4.8</b> | V     |
|                               | Gate Drive UVLO hysteresis |                    |            | 490 |            | mV    |

- (1) All limits are ensured. All electrical characteristics having room temperature limits are tested during production with T<sub>A</sub> = T<sub>J</sub> = 25°C. All hot and cold limits are ensured by correlating the electrical characteristics to process and temperature variations and applying statistical process control.

## Electrical Characteristics (continued)

Specifications with standard typeface are for  $T_J = 25^\circ\text{C}$ , and those with **boldface** type apply over full **Operating Junction Temperature range**.  $V_{IN} = 48\text{V}$ , unless otherwise stated<sup>(1)</sup>.

| Symbol                               | Parameter                    | Conditions  | Min          | Typ   | Max          | Units              |
|--------------------------------------|------------------------------|---|--------------|-------|--------------|--------------------|
|                                      | Pre-charge switch voltage    | At 1 mA   |              | 0.8   |              | V                  |
|                                      | Pre-charge switch on-time    |   |              | 150   |              | ns                 |
| <b>Current Limit</b>                 |                              |   |              |       |              |                    |
|                                      | Current Limit Threshold      |   | <b>0.24</b>  | 0.3   | <b>0.36</b>  | A                  |
|                                      | Current Limit Response Time  | $I_{\text{switch}}$ Overdrive = 0.1A<br>Time to Switch Off    |              | 350   |              | ns                 |
| $T_{\text{OFF-1}}$                   | OFF time generator           | FB=0V, $R_{\text{CL}} = 100\text{K}$                          |              | 35    |              | $\mu\text{s}$      |
| $T_{\text{OFF-2}}$                   | OFF time generator           | FB=2.3V, $R_{\text{CL}} = 100\text{K}$                        |              | 2.56  |              | $\mu\text{s}$      |
| <b>On Time Generator</b>             |                              |   |              |       |              |                    |
|                                      | $T_{\text{ON}} - 1$          | $V_{\text{in}} = 10\text{V}$<br>$R_{\text{on}} = 200\text{K}$ | <b>2.15</b>  | 2.77  | <b>3.5</b>   | $\mu\text{s}$      |
|                                      | $T_{\text{ON}} - 2$          | $V_{\text{in}} = 95\text{V}$<br>$R_{\text{on}} = 200\text{K}$ | <b>200</b>   | 300   | <b>420</b>   | ns                 |
|                                      | Remote Shutdown Threshold    | Rising  | <b>0.40</b>  | 0.70  | <b>1.05</b>  | V                  |
|                                      | Remote Shutdown Hysteresis   |   |              | 35    |              | mV                 |
| <b>Minimum Off Time</b>              |                              |   |              |       |              |                    |
|                                      | Minimum Off Timer            | FB = 0V   |              | 300   |              | ns                 |
| <b>Regulation and OV Comparators</b> |                              |   |              |       |              |                    |
|                                      | FB Reference Threshold       | Internal reference<br>Trip point for switch ON                | <b>2.445</b> | 2.5   | <b>2.550</b> | V                  |
|                                      | FB Over-Voltage Threshold    | Trip point for switch OFF                                     |              | 2.875 |              | V                  |
|                                      | FB Bias Current              |   |              | 100   |              | nA                 |
| <b>Thermal Shutdown</b>              |                              |   |              |       |              |                    |
| $T_{\text{sd}}$                      | Thermal Shutdown Temperature |   |              | 165   |              | $^\circ\text{C}$   |
|                                      | Thermal Shutdown Hysteresis  |   |              | 25    |              | $^\circ\text{C}$   |
| <b>Thermal Resistance</b>            |                              |   |              |       |              |                    |
| $\theta_{\text{JA}}$                 | Junction to Ambient          | WSOP Package  |              | 40    |              | $^\circ\text{C/W}$ |
|                                      |                              | VSSOP Package   |              | 200   |              |                    |

## Typical Performance Characteristics

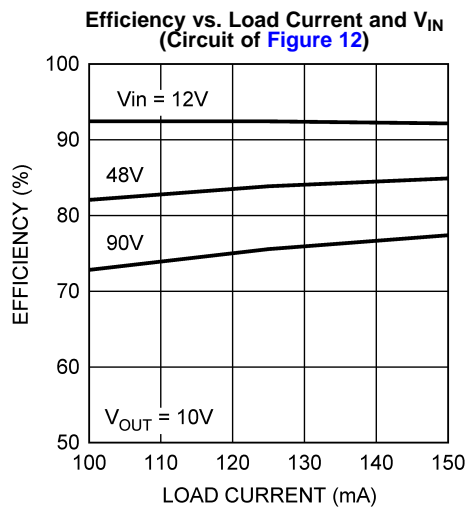


Figure 3.

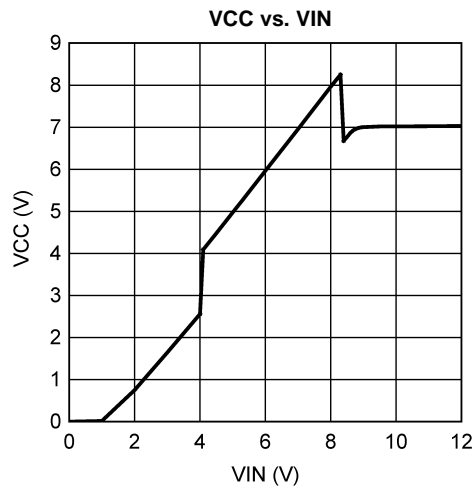


Figure 4.

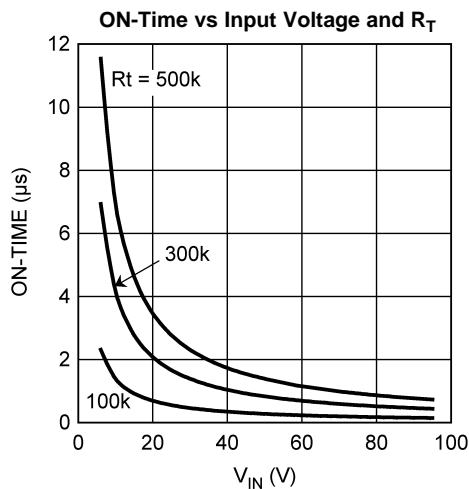


Figure 5.

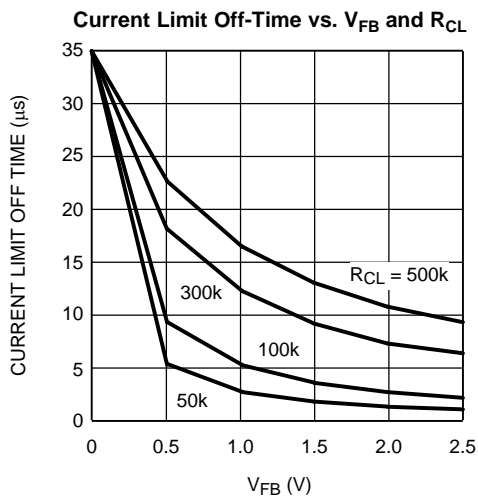


Figure 6.

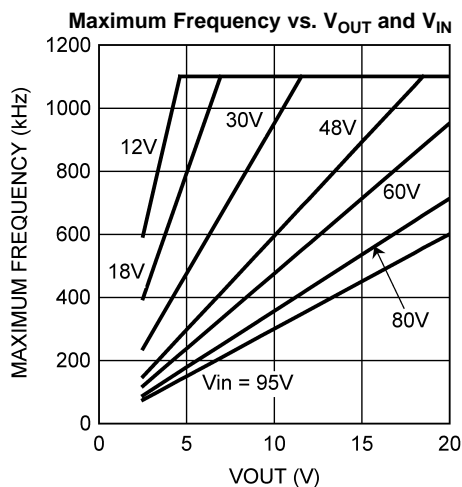


Figure 7.

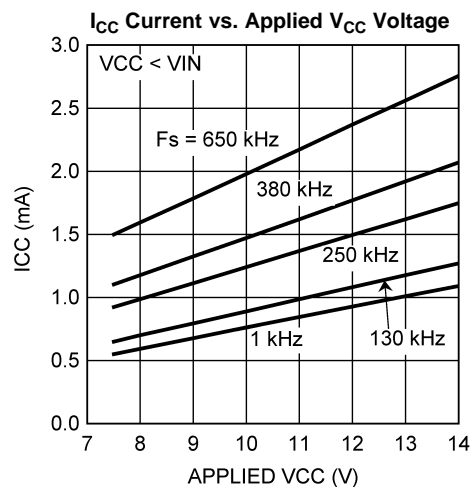
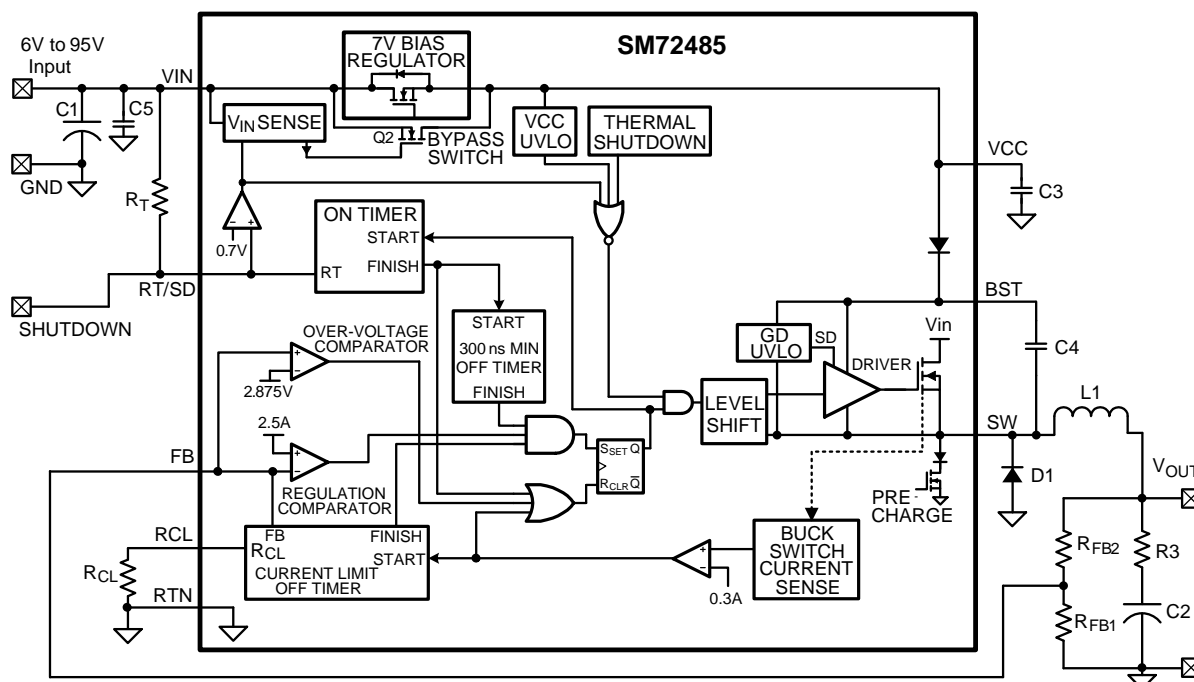


Figure 8.

## BLOCK DIAGRAM



## FUNCTIONAL DESCRIPTION

The SM72485 Step Down Switching Regulator features all the functions needed to implement a low cost, efficient, Buck bias power converter. This high voltage regulator contains a 100 V N-Channel Buck Switch, is easy to implement and is provided in the VSSOP and the thermally enhanced WSON package. The regulator is based on a control scheme using an on-time inversely proportional to  $V_{IN}$ . The control scheme requires no loop compensation. Current limit is implemented with forced off-time, which is inversely proportional to  $V_{OUT}$ . This scheme ensures short circuit control while providing minimum foldback.

The SM72485 can be applied in numerous applications to efficiently regulate down higher voltages. This regulator is well suited for high voltage PV panel junction boxes, 48 Volt Telecom and the new 42V Automotive power bus ranges. Features include: Thermal Shutdown,  $V_{CC}$  under-voltage lockout, Gate drive under-voltage lockout, Max Duty Cycle limit timer, intelligent current limit off timer, and a pre-charge switch.

### Control Circuit Overview

The SM72485 is a Buck DC-DC regulator that uses a control scheme in which the on-time varies inversely with line voltage ( $V_{IN}$ ). Control is based on a comparator and the on-time one-shot, with the output voltage feedback (FB) compared to an internal reference (2.5V). If the FB level is below the reference the buck switch is turned on for a fixed time determined by the line voltage and a programming resistor ( $R_T$ ). Following the ON period the switch will remain off for at least the minimum off-timer period of 300ns. If FB is still below the reference at that time the switch will turn on again for another on-time period. This will continue until regulation is achieved.

The SM72485 operates in discontinuous conduction mode at light load currents, and continuous conduction mode at heavy load current. In discontinuous conduction mode, current through the output inductor starts at zero and ramps up to a peak during the on-time, then ramps back to zero before the end of the off-time. The next on-time period starts when the voltage at FB falls below the internal reference - until then the inductor current remains zero. In this mode the operating frequency is lower than in continuous conduction mode, and varies with load current. Therefore at light loads the conversion efficiency is maintained, since the switching losses reduce with the reduction in load and frequency. The discontinuous operating frequency can be calculated as follows:

$$F = \frac{V_{OUT}^2 \times L \times 1.04 \times 10^{20}}{R_L \times (R_T)^2}$$

where

- $R_L$  = the load resistance (1)

In continuous conduction mode, current flows continuously through the inductor and never ramps down to zero. In this mode the operating frequency is greater than the discontinuous mode frequency and remains relatively constant with load and line variations. The approximate continuous mode operating frequency can be calculated as follows:

$$F = \frac{V_{OUT}}{1.385 \times 10^{-10} \times R_T} \quad (2)$$

The output voltage ( $V_{OUT}$ ) is programmed by two external resistors as shown in the Block Diagram. The regulation point can be calculated as follows:

$$V_{OUT} = 2.5 \times (R_{FB1} + R_{FB2}) / R_{FB1} \quad (3)$$

The SM72485 regulates the output voltage based on ripple voltage at the feedback input, requiring a minimum amount of ESR for the output capacitor C2. A minimum of 25mV to 50mV of ripple voltage at the feedback pin (FB) is required for the SM72485. In cases where the capacitor ESR is too small, additional series resistance (R3 in the Block Diagram) may be required (R3 in the Block Diagram).

For applications where lower output voltage ripple is required the output can be taken directly from a low ESR output capacitor, as shown in Figure 9. However, R3 slightly degrades the load regulation.

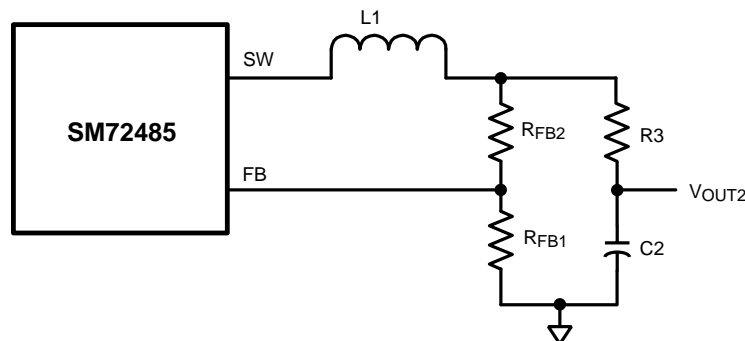


Figure 9. Low Ripple Output Configuration

## Start-Up Regulator ( $V_{CC}$ )

The high voltage bias regulator is integrated within the SM72485. The input pin ( $V_{IN}$ ) can be connected directly to line voltages between 6V and 95V, with transient capability to 100V. Referring to the block diagram and the graph of  $V_{CC}$  vs  $V_{IN}$ , when  $V_{IN}$  is between 6V and the bypass threshold (nominally 8.5V), the bypass switch (Q2) is on, and  $V_{CC}$  tracks  $V_{IN}$  within 100 mV to 150 mV. The bypass switch on-resistance is approximately 100Ω, with inherent current limiting at approximately 100 mA. When  $V_{IN}$  is above the bypass threshold Q2 is turned off, and  $V_{CC}$  is regulated at 7V. The  $V_{CC}$  regulator output current is limited at approximately 9.2 mA. When the SM72485 is shutdown using the RT/SD pin, the  $V_{CC}$  bypass switch is shut off regardless of the voltage at  $V_{IN}$ .

When  $V_{IN}$  exceeds the bypass threshold, the time required for Q2 to shut off is approximately 2 - 3 μs. The capacitor at  $V_{CC}$  (C3) must be a minimum of 0.47 μF to prevent the voltage at  $V_{CC}$  from rising above its absolute maximum rating in response to a step input applied at  $V_{IN}$ . C3 must be located as close as possible to the  $V_{CC}$  and RTN pins. In applications with a relatively high input voltage, power dissipation in the bias regulator is a concern. An auxiliary voltage of between 7.5V and 14V can be diode connected to the  $V_{CC}$  pin to shut off the  $V_{CC}$  regulator, thereby reducing internal power dissipation. The current required into the  $V_{CC}$  pin is shown in the graph "I<sub>CC</sub> Current vs. Applied  $V_{CC}$  Voltage". Internally a diode connects  $V_{CC}$  to  $V_{IN}$  requiring that the auxiliary voltage be less than  $V_{IN}$ .

The turn-on sequence is shown in Figure 10. During the initial delay ( $t_1$ )  $V_{CC}$  ramps up at a rate determined by its current limit and C3 while internal circuitry stabilizes. When  $V_{CC}$  reaches the upper threshold of its under-voltage lock-out (UVLO, typically 5.3V) the buckswitch is enabled. The inductor current increases to the current limit threshold ( $I_{LIM}$ ) and during  $t_2$   $V_{OUT}$  increases as the output capacitor charges up. When  $V_{OUT}$  reaches the intended voltage the average inductor current decreases ( $t_3$ ) to the nominal load current ( $I_O$ ).

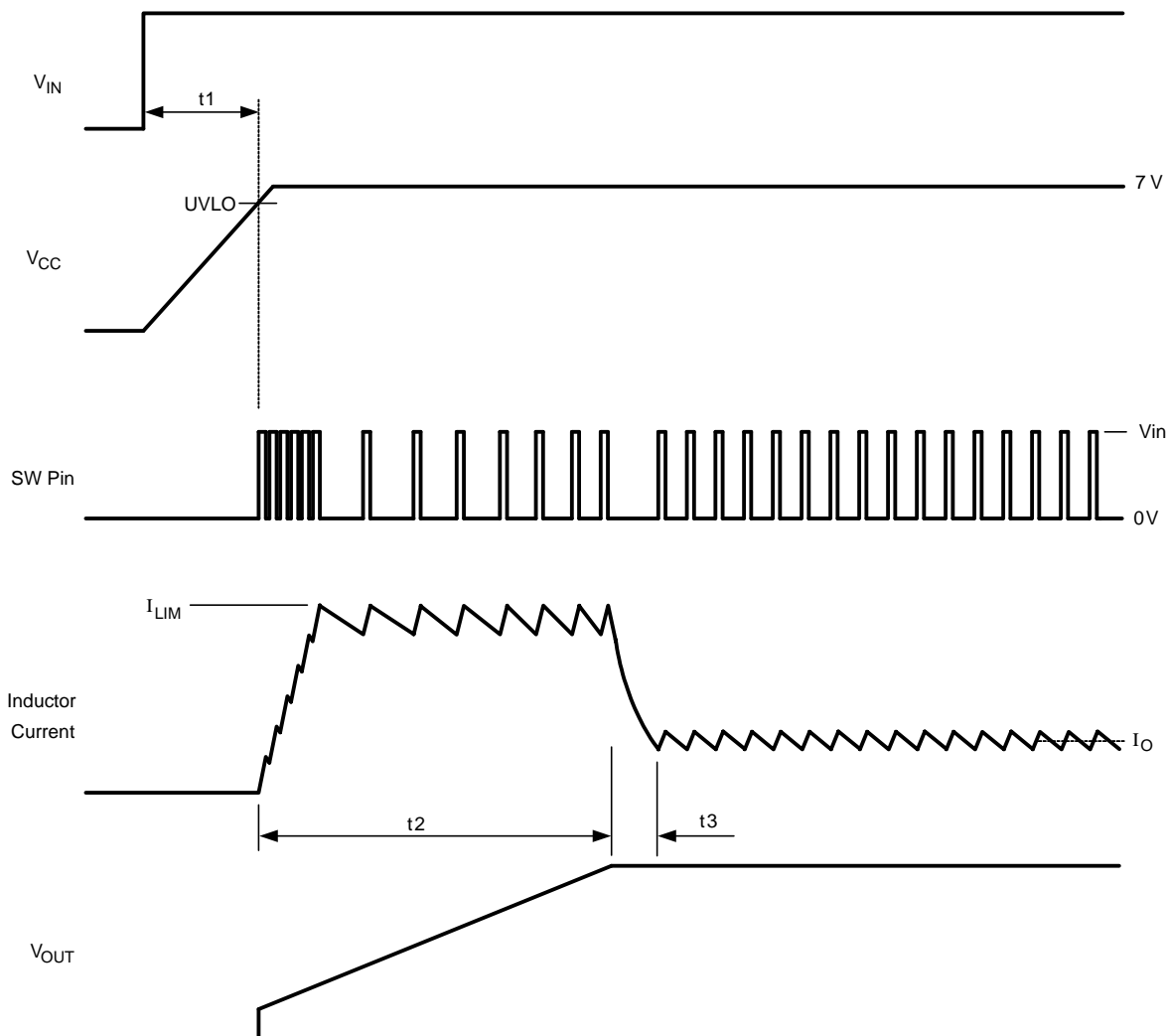


Figure 10. Startup Sequence

### Regulation Comparator

The feedback voltage at FB is compared to an internal 2.5V reference. In normal operation (the output voltage is regulated), an on-time period is initiated when the voltage at FB falls below 2.5V. The buck switch will stay on for the on-time, causing the FB voltage to rise above 2.5V. After the on-time period, the buck switch will stay off until the FB voltage again falls below 2.5V. During start-up, the FB voltage will be below 2.5V at the end of each on-time, resulting in the minimum off-time of 300 ns. Bias current at the FB pin is nominally 100 nA.

### Over-Voltage Comparator

The feedback voltage at FB is compared to an internal 2.875V reference. If the voltage at FB rises above 2.875V the on-time pulse is immediately terminated. This condition can occur if the input voltage, or the output load, change suddenly. The buck switch will not turn on again until the voltage at FB falls below 2.5V.

## On-Time Generator and Shutdown

The on-time for the SM72485 is determined by the  $R_T$  resistor, and is inversely proportional to the input voltage ( $V_{IN}$ ), resulting in a nearly constant frequency as  $V_{IN}$  is varied over its range. The on-time equation for the SM72485 is:

$$T_{ON} = 1.385 \times 10^{-10} \times R_T / V_{IN} \quad (4)$$

$R_T$  should be selected for a minimum on-time (at maximum  $V_{IN}$ ) greater than 400 ns, for proper current limit operation. This requirement limits the maximum frequency for each application, depending on  $V_{IN}$  and  $V_{OUT}$ .

The SM72485 can be remotely disabled by taking the  $R_T/SD$  pin to ground. See Figure 11. The voltage at the  $R_T/SD$  pin is between 1.5 and 3.0 volts, depending on  $V_{IN}$  and the value of the  $R_T$  resistor.

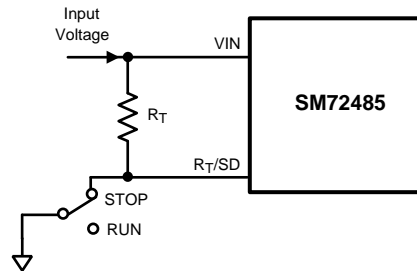


Figure 11. Shutdown Implementation

## Current Limit

The SM72485 contains an intelligent current limit OFF timer. If the current in the Buck switch exceeds 0.3A the present cycle is immediately terminated, and a non-resetable OFF timer is initiated. The length of off-time is controlled by an external resistor ( $R_{CL}$ ) and the FB voltage (see Figure 6). When  $FB = 0V$ , a maximum off-time is required, and the time is preset to 35 $\mu$ s. This condition occurs when the output is shorted, and during the initial part of start-up. This amount of time ensures safe short circuit operation up to the maximum input voltage of 95V. In cases of overload where the FB voltage is above zero volts (not a short circuit) the current limit off-time will be less than 35 $\mu$ s. Reducing the off-time during less severe overloads reduces the amount of foldback, recovery time, and the start-up time. The off-time is calculated from the following equation:

$$T_{OFF} = 10^{-5} / (0.285 + (V_{FB} / 6.35 \times 10^{-6} \times R_{CL})) \quad (5)$$

The current limit sensing circuit is blanked for the first 50-70ns of each on-time so it is not falsely tripped by the current surge which occurs at turn-on. The current surge is required by the re-circulating diode (D1) for its turn-off recovery.

## N-Channel Buck Switch and Driver

The SM72485 integrates an N-Channel Buck switch and associated floating high voltage gate driver. The gate driver circuit works in conjunction with an external bootstrap capacitor and an internal high voltage diode. A 0.01  $\mu$ F ceramic capacitor (C4) connected between the BST pin and SW pin provides the voltage to the driver during the on-time.

During each off-time, the SW pin is at approximately 0V, and the bootstrap capacitor charges from  $V_{CC}$  through the internal diode. The minimum OFF timer, set to 300ns, ensures a minimum time each cycle to recharge the bootstrap capacitor.

The internal pre-charge switch at the SW pin is turned on for  $\approx 150$  ns during the minimum off-time period, ensuring sufficient voltage exists across the bootstrap capacitor for the on-time. This feature helps prevent operating problems which can occur during very light load conditions, involving a long off-time, during which the voltage across the bootstrap capacitor could otherwise reduce below the Gate Drive UVLO threshold. The pre-charge switch also helps prevent startup problems which can occur if the output voltage is pre-charged prior to turn-on. After current limit detection, the pre-charge switch is turned on for the entire duration of the forced off-time.

## Thermal Protection

The SM72485 should be operated so the junction temperature does not exceed 125°C during normal operation. An internal Thermal Shutdown circuit is provided to shutdown the SM72485 in the event of a higher than normal junction temperature. When activated, typically at 165°C, the controller is forced into a low power reset state by disabling the buck switch. This feature prevents catastrophic failures from accidental device overheating. When the junction temperature reduces below 140°C (typical hysteresis = 25°C) normal operation is resumed.

## APPLICATIONS INFORMATION

### SELECTION OF EXTERNAL COMPONENTS

A guide for determining the component values will be illustrated with a design example. Refer to the Block Diagram. The following steps will configure the SM72485 for:

- Input voltage range ( $V_{IN}$ ): 12V to 90V
- Output voltage ( $V_{OUT1}$ ): 10V
- Load current (for continuous conduction mode): 100 mA to 150 mA

**$R_{FB1}$ ,  $R_{FB2}$ :**  $V_{OUT} = V_{FB} \times (R_{FB1} + R_{FB2}) / R_{FB1}$ , and since  $V_{FB} = 2.5V$ , the ratio of  $R_{FB2}$  to  $R_{FB1}$  calculates as 3:1. Standard values of 3.01 k $\Omega$  and 1.00 k $\Omega$  are chosen. Other values could be used as long as the 3:1 ratio is maintained.

**$F_s$  and  $R_T$ :** The recommended operating frequency range for the SM72485 is 50 kHz to 1.1 MHz. Unless the application requires a specific frequency, the choice of frequency is generally a compromise since it affects the size of L1 and C2, and the switching losses. The maximum allowed frequency, based on a minimum on-time of 400 ns, is calculated from:

$$F_{MAX} = V_{OUT} / (V_{INMAX} \times 400 \text{ ns}) \quad (6)$$

For this exercise,  $F_{max} = 277 \text{ kHz}$ . From Equation 2,  $R_T$  calculates to 260 k $\Omega$ . A standard value 309 k $\Omega$  resistor will be used to allow for tolerances in Equation 2, resulting in a frequency of 234 kHz.

**L1:** The main parameter affected by the inductor is the output current ripple amplitude. The choice of inductor value therefore depends on both the minimum and maximum load currents, keeping in mind that the maximum ripple current occurs at maximum  $V_{IN}$ .

a) **Minimum load current:** To maintain continuous conduction at minimum  $I_O$  (100 mA), the ripple amplitude ( $I_{OR}$ ) must be less than 200 mA p-p so the lower peak of the waveform does not reach zero. L1 is calculated using the following equation:

$$L1 = \frac{V_{OUT} \times (V_{IN} - V_{OUT})}{I_{OR} \times F_s \times V_{IN}} \quad (7)$$

At  $V_{IN} = 90V$ ,  $L1(\text{min})$  calculates to 190  $\mu H$ . The next larger standard value (220  $\mu H$ ) is chosen and with this value  $I_{OR}$  calculates to 173 mA p-p at  $V_{IN} = 90V$ , and 32 mA p-p at  $V_{IN} = 12V$ .

b) **Maximum load current:** At a load current of 150 mA, the peak of the ripple waveform must not reach the minimum ensured value of the SM72485's current limit threshold (240 mA). Therefore the ripple amplitude must be less than 180 mA p-p, which is already satisfied in the above calculation. With  $L1 = 220 \mu H$ , at maximum  $V_{IN}$  and  $I_O$ , the peak of the ripple will be 236 mA. While L1 must carry this peak current without saturating or exceeding its temperature rating, it also must be capable of carrying the maximum specified value of the SM72485's current limit threshold (360 mA) without saturating, since the current limit is reached during startup.

The DC resistance of the inductor should be as low as possible to minimize its power loss.

**C3:** The capacitor on the  $V_{CC}$  output provides not only noise filtering and stability, but its primary purpose is to prevent false triggering of the  $V_{CC}$  UVLO at the buck switch on/off transitions. C3 should be no smaller than 0.47  $\mu F$ .

**C2, and R3:** When selecting the output filter capacitor C2, the items to consider are ripple voltage due to its ESR, ripple voltage due to its capacitance, and the nature of the load.

**ESR and R3:** A low ESR for C2 is generally desirable so as to minimize power losses and heating within the capacitor. However, the regulator requires a minimum amount of ripple voltage at the feedback input for proper loop operation. For the SM72485 the minimum ripple required at pin 5 is 25 mV p-p, requiring a minimum ripple at  $V_{OUT}$  of 100 mV. Since the minimum ripple current (at minimum  $V_{in}$ ) is 32 mA p-p, the minimum ESR required at  $V_{OUT}$  is  $100 \text{ mV} / 32 \text{ mA} = 3.12 \Omega$ . Since quality capacitors for SMPS applications have an ESR considerably less than this, R3 is inserted as shown in the Block Diagram. R3's value, along with C2's ESR, must result in at least 25 mV p-p ripple at pin 5. Generally, R3 will be 0.5 to  $4.0 \Omega$ .

**R<sub>CL</sub>:** When current limit is detected, the minimum off-time set by this resistor must be greater than the maximum normal off-time, which occurs at maximum input voltage. Using Equation 4, the minimum on-time is 476 ns, yielding an off-time of 3.8  $\mu\text{s}$  (at 234 kHz). Due to the 25% tolerance on the on-time, the off-time tolerance is also 25%, yielding a maximum off-time of 4.75  $\mu\text{s}$ . Allowing for the response time of the current limit detection circuit (350 ns) increases the maximum off-time to 5.1  $\mu\text{s}$ . This is increased an additional 25% to 6.4  $\mu\text{s}$  to allow for the tolerances of Equation 5. Using Equation 5,  $R_{CL}$  calculates to 310 k $\Omega$  at  $V_{FB} = 2.5\text{V}$ . A standard value 316 k $\Omega$  resistor will be used.

**D1:** The important parameters are reverse recovery time and forward voltage. The reverse recovery time determines how long the reverse current surge lasts each time the buck switch is turned on. The forward voltage drop is significant in the event the output is short-circuited as it is only this diode's voltage which forces the inductor current to reduce during the forced off-time. For this reason, a higher voltage is better, although that affects efficiency. A good choice is a Schottky power diode, such as the DFLS1100. D1's reverse voltage rating must be at least as great as the maximum  $V_{in}$ , and its current rating be greater than the maximum current limit threshold (360 mA).

**C1:** This capacitor's purpose is to supply most of the switch current during the on-time, and limit the voltage ripple at  $V_{in}$ , on the assumption that the voltage source feeding  $V_{in}$  has an output impedance greater than zero. At maximum load current, when the buck switch turns on, the current into pin 8 will suddenly increase to the lower peak of the output current waveform, ramp up to the peak value, then drop to zero at turn-off. The average input current during this on-time is the load current (150 mA). For a worst case calculation, C1 must supply this average load current during the maximum on-time. To keep the input voltage ripple to less than 2V (for this exercise), C1 calculates to:

$$C1 = \frac{I \times t_{ON}}{\Delta V} = \frac{0.15\text{A} \times 3.57 \mu\text{s}}{2.0\text{V}} = 0.268 \mu\text{F} \quad (8)$$

Quality ceramic capacitors in this value have a low ESR which adds only a few millivolts to the ripple. It is the capacitance which is dominant in this case. To allow for the capacitor's tolerance, temperature effects, and voltage effects, a 1.0  $\mu\text{F}$ , 100V, X7R capacitor will be used.

**C4:** The recommended value is 0.01 $\mu\text{F}$  for C4, as this is appropriate in the majority of applications. A high quality ceramic capacitor, with low ESR is recommended as C4 supplies the surge current to charge the buck switch gate at turn-on. A low ESR also ensures a quick recharge during each off-time. At minimum  $V_{in}$ , when the on-time is at maximum, it is possible during start-up that C4 will not fully recharge during each 300 ns off-time. The circuit will not be able to complete the start-up, and achieve output regulation. This can occur when the frequency is intended to be low (e.g.,  $R_T = 500\text{K}$ ). In this case C4 should be increased so it can maintain sufficient voltage across the buck switch driver during each on-time.

**C5:** This capacitor helps avoid supply voltage transients and ringing due to long lead inductance at  $V_{IN}$ . A low ESR, 0.1 $\mu\text{F}$  ceramic chip capacitor is recommended, located close to the SM72485.

## FINAL CIRCUIT

The final circuit is shown in Figure 12. The circuit was tested, and the resulting performance is shown in Figure 13 and Figure 14.

## PC BOARD LAYOUT

The SM72485 regulation and over-voltage comparators are very fast, and as such will respond to short duration noise pulses. Layout considerations are therefore critical for optimum performance. The components at pins 1, 2, 3, 5, and 6 should be as physically close as possible to the IC, thereby minimizing noise pickup in the PC tracks. The current loop formed by D1, L1, and C2 should be as small as possible. The ground connection from D1 to C1 should be as short and direct as possible.

If the internal dissipation of the SM72485 produces excessive junction temperatures during normal operation, good use of the PC board's ground plane can help considerably to dissipate heat. The exposed pad on the bottom of the WSON package can be soldered to a ground plane on the PC board, and that plane should extend out from beneath the IC to help dissipate the heat. Additionally, the use of wide PC board traces, where possible, can also help conduct heat away from the IC. Judicious positioning of the PC board within the end product, along with use of any available air flow (forced or natural convection) can help reduce the junction temperatures.

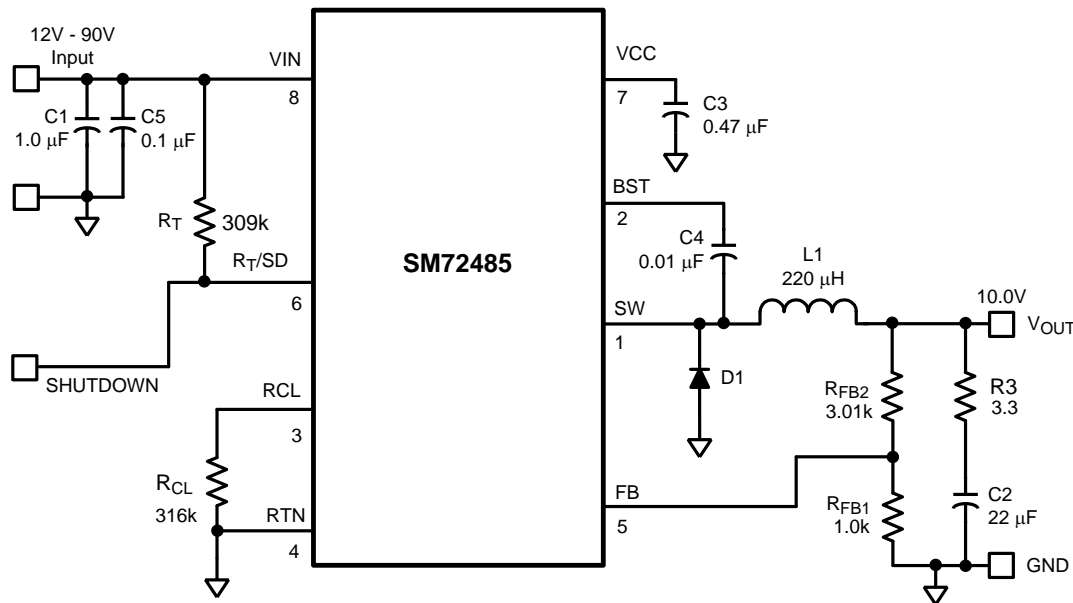
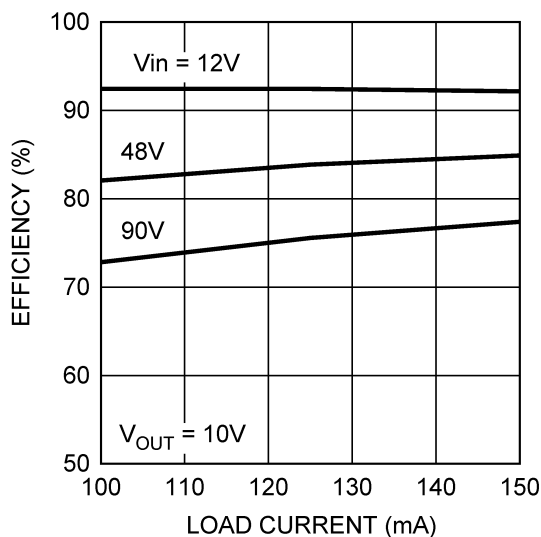


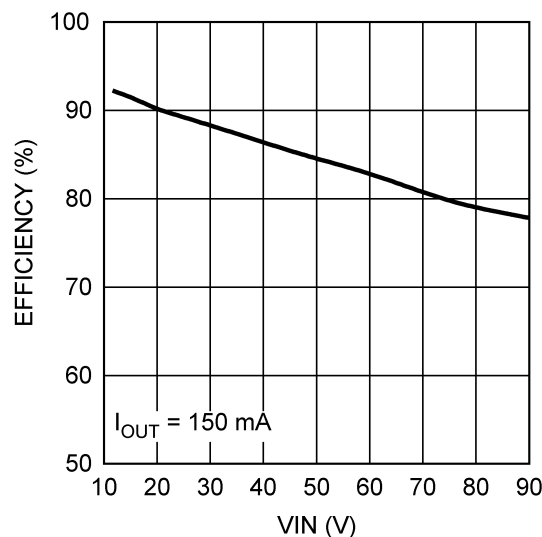
Figure 12. SM72485 Example Circuit

Table 1. Bill of Materials

| Item             | Description          | Part Number  | Value        |
|------------------|----------------------|--|--------------|
| C1               | Ceramic Capacitor    | TDK C4532X7R2A105M                                   | 1 µF, 100V   |
| C2               | Ceramic Capacitor    | TDK C4532X7R1E226M                                   | 22 µF, 25V   |
| C3               | Ceramic Capacitor    | Kemet C1206C474K5RAC                                 | 0.47 µF, 50V |
| C4               | Ceramic Capacitor    | Kemet C1206C103K5RAC                                 | 0.01 µF, 50V |
| C5               | Ceramic Capacitor    | TDK C3216X7R2A104M                                   | 0.1 µF, 100V |
| D1               | Schottky Power Diode | Diodes Inc. DFLS1100                                 | 100V, 1A     |
| L1               | Power Inductor       | COILTRONICS DR125-221-R, or<br>TDK SLF10145T-221MR65 | 220 µH       |
| R <sub>FB2</sub> | Resistor             | Vishay CRCW12063011F                                 | 3.01 kΩ      |
| R <sub>FB1</sub> | Resistor             | Vishay CRCW12061001F                                 | 1.0 kΩ       |
| R3               | Resistor             | Vishay CRCW12063R30F                                 | 3.3 Ω        |
| R <sub>T</sub>   | Resistor             | Vishay CRCW12063093F                                 | 309 kΩ       |
| R <sub>CL</sub>  | Resistor             | Vishay CRCW12063163F                                 | 316 kΩ       |
| U1               | Switching Regulator  | Texas Instruments SM72485                            |              |



**Figure 13. Efficiency vs. Load Current and  $V_{IN}$**



**Figure 14. Efficiency vs.  $V_{IN}$**

## LOW OUTPUT RIPPLE CONFIGURATIONS

For applications where low output ripple is required, the following options can be used to reduce or nearly eliminate the ripple.

**a) Reduced ripple configuration:** In Figure 15,  $C_{ff}$  is added across  $R_{FB2}$  to AC-couple the ripple at  $V_{OUT}$  directly to the FB pin. This allows the ripple at  $V_{OUT}$  to be reduced to a minimum of 25 mVp-p by reducing  $R_3$ , since the ripple at  $V_{OUT}$  is not attenuated by the feedback resistors. The minimum value for  $C_{ff}$  is determined from:

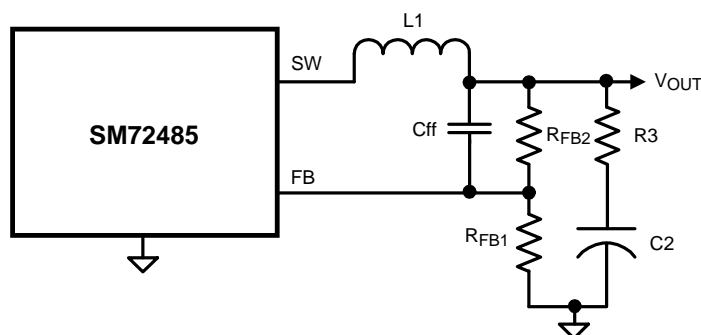
$$C_{ff} = \frac{3 \times t_{ON(max)}}{(R_{FB1} // R_{FB2})}$$

where

- $t_{ON(max)}$  is the maximum on-time which occurs at  $V_{IN(min)}$
- 

(9)

The next larger standard value capacitor should be used for  $C_{ff}$ .



**Figure 15. Reduced Ripple Configuration**

**b) Minimum ripple configuration:** If the application requires a lower value of ripple (<10 mVp-p), the circuit of Figure 16 can be used.  $R_3$  is removed, and the resulting output ripple voltage is determined by the inductor's ripple current and  $C_2$ 's characteristics.  $R_A$  and  $C_A$  are chosen to generate a sawtooth waveform at their junction, and that voltage is AC-coupled to the FB pin via  $C_B$ . To determine the values for  $R_A$ ,  $C_A$  and  $C_B$ , use the following procedure:

$$\text{Calculate } V_A = V_{OUT} - (V_{SW} \times (1 - (V_{OUT}/V_{IN(min)})))$$

where

- $V_{SW}$  is the absolute value of the voltage at the SW pin during the off-time (typically 1V) (10)

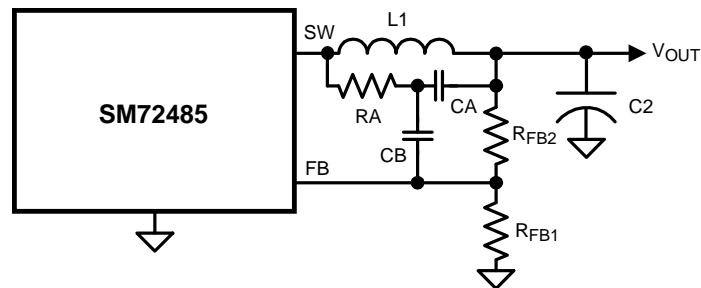
$V_A$  is the DC voltage at the RA/CA junction, and is used in the next equation.

$$\text{Calculate } RA \times CA = (V_{IN(min)} - V_A) \times t_{ON}/\Delta V$$

where

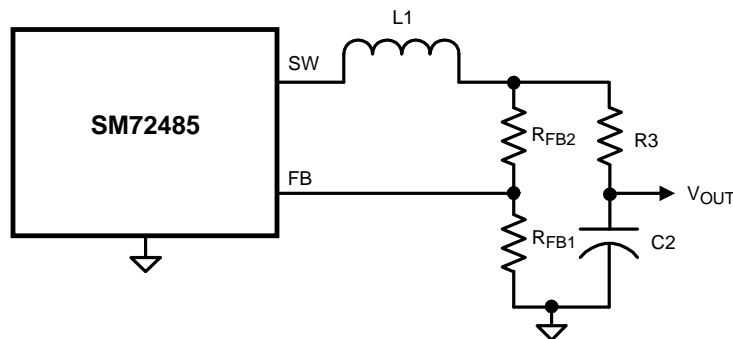
- $t_{ON}$  is the maximum on-time (at minimum input voltage)
- $\Delta V$  is the desired ripple amplitude at the RA/CA junction (typically 40-50 mV) (11)

$RA$  and  $CA$  are then chosen from standard value components to satisfy the above product. Typically  $CA$  is 1000 pF to 5000 pF, and  $RA$  is 10 k $\Omega$  to 300 k $\Omega$ .  $CB$  is then chosen large compared to  $CA$ , typically 0.1  $\mu$ F.



**Figure 16. Minimum Output Ripple Using Ripple Injection**

**c) Alternate minimum ripple configuration:** The circuit in Figure 17 is the same as that in the Block Diagram, except the output voltage is taken from the junction of  $R_3$  and  $C_2$ . The ripple at  $V_{OUT}$  is determined by the inductor's ripple current and  $C_2$ 's characteristics. However,  $R_3$  slightly degrades the load regulation. This circuit may be suitable if the load current is fairly constant.



**Figure 17. Alternate Minimum Output Ripple**

## REVISION HISTORY

| Changes from Revision C (April 2013) to Revision D         | Page               |
|--|--------------------|
| • Changed layout of National Data Sheet to TI format ..... | <a href="#">14</a> |

## PACKAGING INFORMATION

| Orderable Device | Status<br>(1) | Package Type | Package<br>Drawing | Pins | Package<br>Qty | Eco Plan<br>(2)            | Lead/Ball Finish | MSL Peak Temp<br>(3) | Op Temp (°C) | Top-Side Markings<br>(4) | Samples                 |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|------------------|----------------------|--------------|--------------------------|-------------------------|
| SM72485MM/NOPB   | ACTIVE        | VSSOP        | DGK                | 8    | 1000           | Green (RoHS<br>& no Sb/Br) | CU SN            | Level-1-260C-UNLIM   | -40 to 125   | 2485                     | <a href="#">Samples</a> |
| SM72485MME/NOPB  | ACTIVE        | VSSOP        | DGK                | 8    | 250            | Green (RoHS<br>& no Sb/Br) | CU SN            | Level-1-260C-UNLIM   | -40 to 125   | 2485                     | <a href="#">Samples</a> |
| SM72485MMX/NOPB  | ACTIVE        | VSSOP        | DGK                | 8    | 3500           | Green (RoHS<br>& no Sb/Br) | CU SN            | Level-1-260C-UNLIM   | -40 to 125   | 2485                     | <a href="#">Samples</a> |
| SM72485SD/NOPB   | ACTIVE        | WSO          | NGU                | 8    | 1000           | Green (RoHS<br>& no Sb/Br) | CU SN            | Level-1-260C-UNLIM   | -40 to 125   | S2485                    | <a href="#">Samples</a> |
| SM72485SDE/NOPB  | ACTIVE        | WSO          | NGU                | 8    | 250            | Green (RoHS<br>& no Sb/Br) | CU SN            | Level-1-260C-UNLIM   | -40 to 125   | S2485                    | <a href="#">Samples</a> |
| SM72485SDX/NOPB  | ACTIVE        | WSO          | NGU                | 8    | 4500           | Green (RoHS<br>& no Sb/Br) | CU SN            | Level-1-260C-UNLIM   | -40 to 125   | S2485                    | <a href="#">Samples</a> |

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

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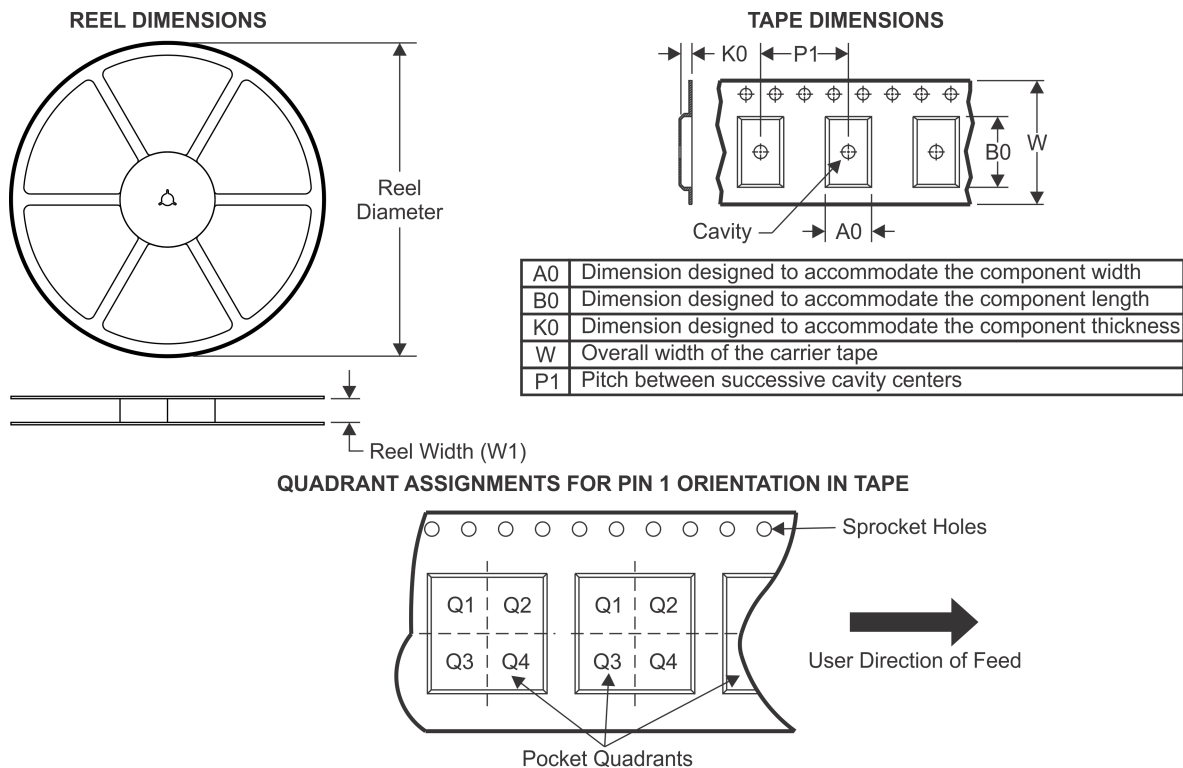
**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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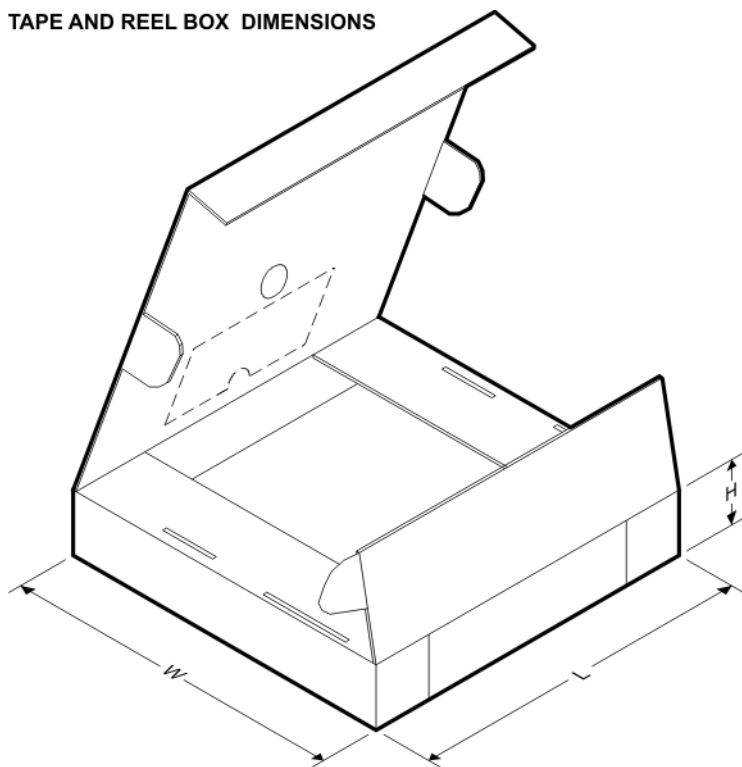
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\*All dimensions are nominal

| Device          | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SM72485MM/NOPB  | VSSOP        | DGK             | 8    | 1000 | 178.0              | 12.4               | 5.3     | 3.4     | 1.4     | 8.0     | 12.0   | Q1            |
| SM72485MME/NOPB | VSSOP        | DGK             | 8    | 250  | 178.0              | 12.4               | 5.3     | 3.4     | 1.4     | 8.0     | 12.0   | Q1            |
| SM72485MMX/NOPB | VSSOP        | DGK             | 8    | 3500 | 330.0              | 12.4               | 5.3     | 3.4     | 1.4     | 8.0     | 12.0   | Q1            |
| SM72485SD/NOPB  | WSO          | NGU             | 8    | 1000 | 178.0              | 12.4               | 4.3     | 4.3     | 1.3     | 8.0     | 12.0   | Q1            |
| SM72485SDE/NOPB | WSO          | NGU             | 8    | 250  | 178.0              | 12.4               | 4.3     | 4.3     | 1.3     | 8.0     | 12.0   | Q1            |
| SM72485SDX/NOPB | WSO          | NGU             | 8    | 4500 | 330.0              | 12.4               | 4.3     | 4.3     | 1.3     | 8.0     | 12.0   | Q1            |

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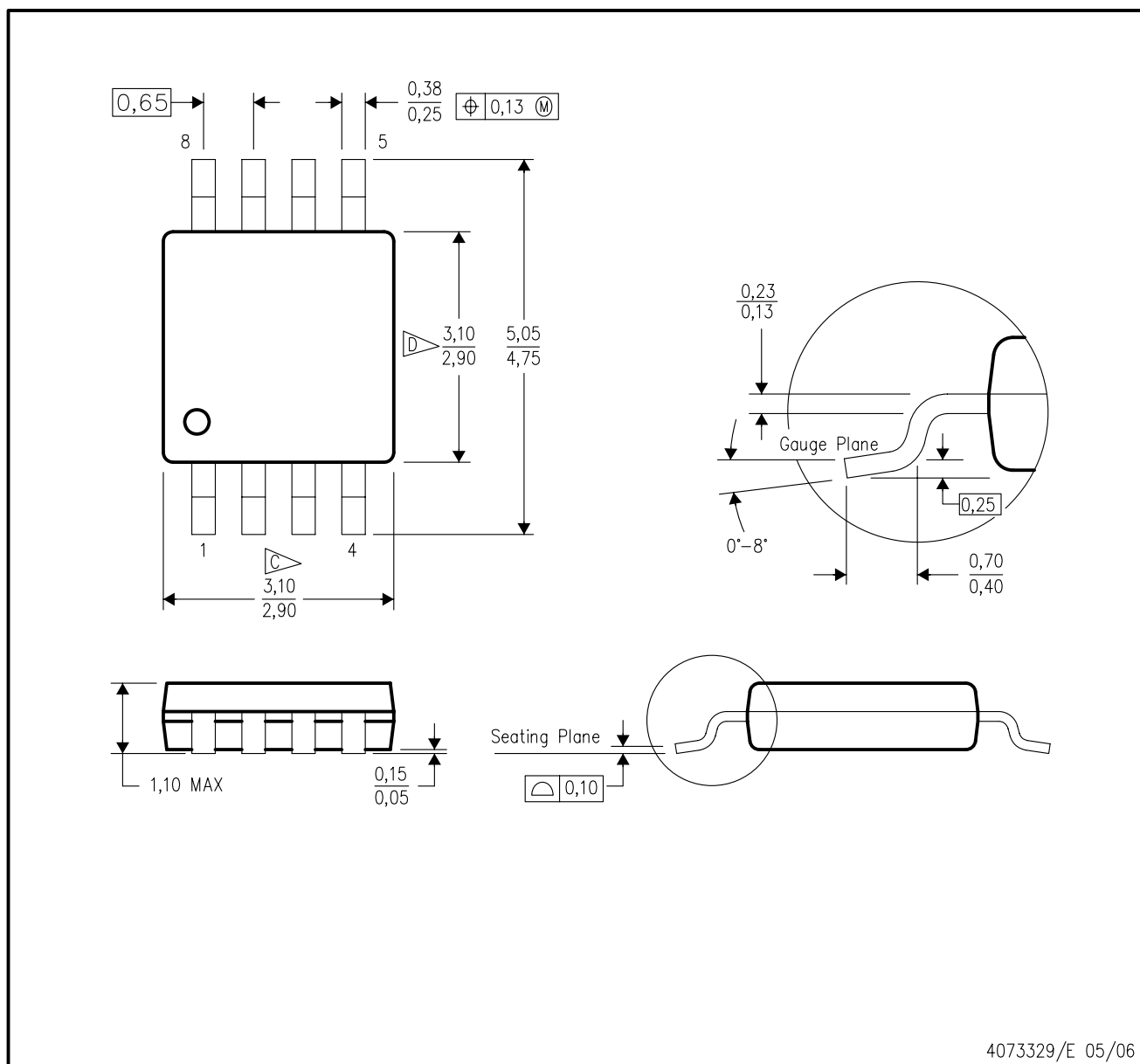


\*All dimensions are nominal

| Device          | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|-----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SM72485MM/NOPB  | VSSOP        | DGK             | 8    | 1000 | 210.0       | 185.0      | 35.0        |
| SM72485MME/NOPB | VSSOP        | DGK             | 8    | 250  | 210.0       | 185.0      | 35.0        |
| SM72485MMX/NOPB | VSSOP        | DGK             | 8    | 3500 | 367.0       | 367.0      | 35.0        |
| SM72485SD/NOPB  | WSON         | NGU             | 8    | 1000 | 210.0       | 185.0      | 35.0        |
| SM72485SDE/NOPB | WSON         | NGU             | 8    | 250  | 210.0       | 185.0      | 35.0        |
| SM72485SDX/NOPB | WSON         | NGU             | 8    | 4500 | 367.0       | 367.0      | 35.0        |

## DGK (S-PDSO-G8)

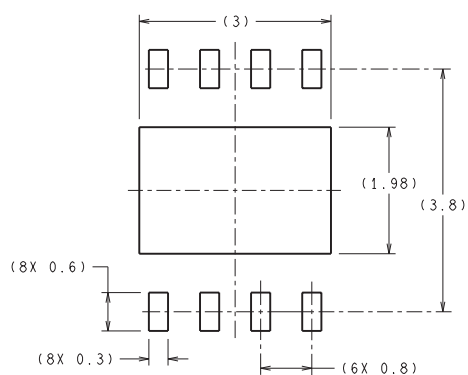
## PLASTIC SMALL-OUTLINE PACKAGE



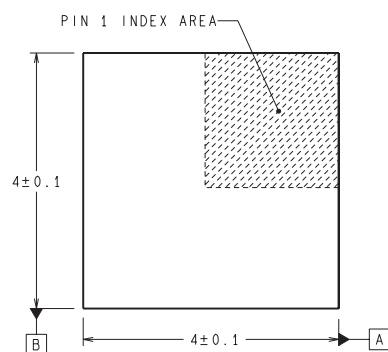
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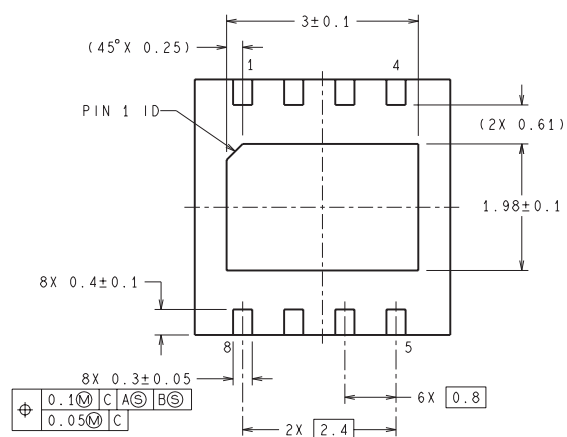
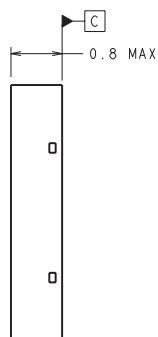
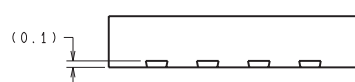
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| RFID                         | <a href="http://www.ti-rfid.com">www.ti-rfid.com</a>                                 |
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| Wireless Connectivity        | <a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a> |

### Applications

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|-------------------------------|--|
| Automotive and Transportation | <a href="http://www.ti.com/automotive">www.ti.com/automotive</a>                         |
| Communications and Telecom    | <a href="http://www.ti.com/communications">www.ti.com/communications</a>                 |
| Computers and Peripherals     | <a href="http://www.ti.com/computers">www.ti.com/computers</a>                           |
| Consumer Electronics          | <a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>                   |
| Energy and Lighting           | <a href="http://www.ti.com/energy">www.ti.com/energy</a>                                 |
| Industrial                    | <a href="http://www.ti.com/industrial">www.ti.com/industrial</a>                         |
| Medical                       | <a href="http://www.ti.com/medical">www.ti.com/medical</a>                               |
| Security                      | <a href="http://www.ti.com/security">www.ti.com/security</a>                             |
| Space, Avionics and Defense   | <a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a> |
| Video and Imaging             | <a href="http://www.ti.com/video">www.ti.com/video</a>                                   |

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